

DERWENT-ACC-NO: 1973-26771U

DERWENT-WEEK: 197319

COPYRIGHT 1999 DERWENT INFORMATION LTD

TITLE: Automatic washing of silicone wafers - for semiconductor
prodn

PATENT-ASSIGNEE: OSAKA TITANIUM CO LTD[OSAN]

PRIORITY-DATA: 1968JP-0078408 (October 28, 1968)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 73014145 B		N/A	000	N/A

INT-CL (IPC): B08B000/00, H01L000/00

ABSTRACTED-PUB-NO: JP 73014145B

BASIC-ABSTRACT:

This invention relates to a method for washing surfaces of a highly pure silicon wafer for a semiconductor element. It is an object of this invention to remove thoroughly and safely from surface of a silicon wafer impurities such as metal powder, abrasives, oils and fats and to carry out continuously automatic operation of washing of a silicon wafer. Method comprises dipping the silicon wafer in a non-combustible, volatile organic solvent having a b.pt. <100 degrees C and washing it ultrasonically, dipping the washed silicon wafer in water heated to > the boiling pt. of the org. solvent or in warm water contg. neutral cleaning material to evaporate the organic solvent, and then dipping the wafer in pure water and subjecting it to further ultrasonic washing treatment. Surface impurities such as metal powder, abrasives, oils and fats are removed.

TITLE-TERMS: AUTOMATIC WASHING SILICONE WAFER SEMICONDUCTOR PRODUCE

DERWENT-CLASS: L03 P43 U12

CPI-CODES: L03-D03;